Product Change Notification / LIAL-25ESGC237

Date:

16-Jun-2021

Product Category:

NVMe/NVRAM - Flashtec

PCN Type:

Manufacturing Change

Notification Subject:

CCB 4592 Final Notice: Qualification of an additional substrate material for PM8607B1-F3EI Microsemi catalog part number (CPN) available in 1085L FBGA (27x27x2.23mm) package at ASE assembly site.

Affected CPNs:

LIAL-25ESGC237_Affected_CPN_06162021.pdf
LIAL-25ESGC237_Affected_CPN_06162021.csv

Notification Text:

PCN Status: Final notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change: Qualification of an additional substrate material for PM8607B1-F3EI Microsemi catalog part number (CPN) available in 1085L FBGA (27x27x2.23mm) package at ASE assembly site.

Pre and Post Change Summary:

	Pre Change	Post Change	
Assembly Site	ASE Inc. (ASE)	ASE Inc. (ASE)	ASE Inc. (ASE)
Bump material	Sn1.8Ag	Sn1.8Ag	Sn1.8Ag
Die attach material	WF6317	WF6317	WF6317

Underfill material	UA28	UA28	UA28
Substrate core material	E700G	E700G	E705G
SM Material	AUS703	AUS703	SR7300
Solder ball material	SAC305	SAC305	SAC305

Impacts to Data Sheet: None

Change Impact: None

Reason for Change: To improve on-time delivery performance by qualifying an an additional substrate material for PM8607B1-F3EI Microsemi catalog part number (CPN) available in 1085L FBGA (27x27x2.23mm) package at ASE assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date:
June 29, 2021 (date code: 2127)

NOTE: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Due to unforeseen circumstances, that are out of Microchip's control, full qualification will be made available as soon as it is approved which may be after the estimated first ship date so that Microchip can maintain continuity of supply and not disrupt customer orders.

Time Table Summary:

	April 2021					**-->**	**June 2021**					**->**	**August 2021**				
Workweek	14	15	16	17	18		23	24	25	26	27		32	33	34	35	36
Initial PCN Issue Date		X															
Qual Report Availability																	X
Final PCN Issue Date									X								
Estimated First Ship Date											X						

Method to Identify Change: Traceability code

Estimated Qualification Completion Date: August 2021

Note 1: This final PCN will be updated to include the Qualification report as soon as it is completed.Note 2: Please be *advised the qualification completion times may be extended because of unforeseen business conditions. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.*

Revision History:April 8, 2021: Issued initial notification.**June 16, 2021:** Issued final notification. Provided estimated first ship date to be on June 29, 2021.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Please contact your local Microchip sales office with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to receive Microchip PCNs via email please register for our PCN email service at our PCN home page select register then fill in the required fields. You will find instructions about registering for Microchips PCN email service in the PCN FAQ section.

If you wish to change your PCN profile, including opt out, please go to the PCN home page select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN)

PM8607B1-F3EI

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Affected Catalog Part Numbers(CPN)

PM8607B1-F3EI